



SMD Comm X7R HV Flex, Ceramic, 0.27 uF, 10%, 500 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X7R HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	185 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1.9mm +/-0.20mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

Packaging Specifications		
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В	0.7mm +/-0.35mm	
S	2.3mm MIN	I
Т	1.9mm +/-0.20mm	,
W	3.2mm +/-0.3mm	-
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Specifications	
Capacitance	0.27 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0 Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	370.4 MOhms

Packaging Specifications		
Packaging	T&R, 330mm, Plastic Tape	
Packaging Quantity	2000	

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